

#### Maximum Ratings and Thermal Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		V <sub>DS</sub>	-60	V	
Gate-Source Voltage		V <sub>GS</sub>	±20		
Continuous Drain Current <sup>(Note 3)</sup>	Tc=25°C	ID	-18		
	Tc=100°C		-13	А	
Pulsed Drain Current <sup>(Note 1)</sup>	T <sub>c</sub> =25°C	I <sub>DM</sub>	-34		
Power Dissipation	T <sub>c</sub> =25°C	_	39	W	
	Tc=100°C	PD	20		
Continuous Drain Current <sup>(Note 4)</sup>	T <sub>A</sub> =25°C		-4.5	Δ	
	T <sub>A</sub> =70 <sup>°</sup> C	Ι <sub>D</sub>	-3.8	A	
Power Dissipation	T <sub>A</sub> =25 <sup>°</sup> C	Po	2.5	W	
	T <sub>A</sub> =70 <sup>°</sup> C		1.8	VV	
Single Pulse Avalanche Current <sup>(Note 5)</sup>		las	8.6	А	
Single Pulse Avalanche Energy <sup>(Note 5)</sup>		Eas	39	mJ	
Operating Junction and Storage Temperature Range		TJ,TSTG	-55~175	°C	
Thermal Resistance <sup>(Note 4)</sup>	Junction to Case	R <sub>θJC</sub>	3.8	°C/W	
	Junction to Ambient	$R_{\theta JA}$	60		



# PJQ44609AP-AU

#### Electrical Characteristics (TA=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Static		-				
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-60	-	-	v
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA	-1	-1.7	-2.5	
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	Vgs=-10V, Id=-6A	-	50	62	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3A	-	64	83	
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> =-60V, V <sub>GS</sub> =0V	-	-	-1	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	$V_{GS}=\pm 20V$ , $V_{DS}=0V$	-	-	±100	nA
Dynamic <sup>(Note 6)</sup>	-			•		
Total Gate Charge	Qg	V <sub>DS</sub> =-30V, I <sub>D</sub> =-6A, V <sub>GS</sub> =-10V	-	22	30	nC
Gate-Source Charge	Qgs		-	3.7	-	
Gate-Drain Charge	$Q_{gd}$	VGS=-10V	-	4.2	-	
Input Capacitance	Ciss	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V, f=1MHz	-	1226	1600	pF
Output Capacitance	Coss		-	70	120	
Reverse Transfer Capacitance	Crss	I=IMHZ	-	54	95	
Gate resistance	Rg	f=1MHz	-	10.5	-	Ω
Turn-On Delay Time	td(on)	V <sub>DS</sub> =-30V, I <sub>D</sub> =-6A, V <sub>GS</sub> =-10V, R <sub>G</sub> =3Ω	-	4.9	-	ns
Turn-On Rise Time	tr		-	2.9	-	
Turn-Off Delay Time	td <sub>(off)</sub>		-	42	-	
Turn-Off Fall Time	tf		-	19	-	
Drain-Source Diode	·	·				
Diode Forward Current	I <sub>S</sub>	T 05°0	-	-	-18	•
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> =25 <sup>°</sup> C	-	-	-34	A
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-6A, V <sub>GS</sub> =0V	-	-0.85	-1.3	V
Reverse Recovery Time	Trr	V <sub>DD</sub> =-30V, V <sub>GS</sub> =0V,	-	22	-	ns
Reverse Recovery Charge	Qrr	Is=-6A,dIs/dt=100A/us	-	11	-	nC

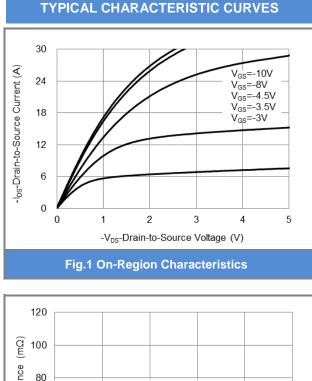
NOTES :

- 1. Pulse width</br>
- 2. Essentially independent of operating temperature typical characteristics.
- 3. The maximum current rating is package limited.
- 4.  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch<sup>2</sup> with 2oz.square pad of copper.
- 5. E<sub>AS</sub> is calculated based on the condition of L=1mH, I<sub>AS</sub>=-8.8A, V<sub>DD</sub>=-30V, V<sub>GS</sub>=-10V. 100% test at L=0.5mH, I<sub>AS</sub>=-8.6A in production.
- 6. Guaranteed by design, not subject to production testing.

SEMI CONDUCTOR

ΡΛΝ

### PJQ44609AP-AU



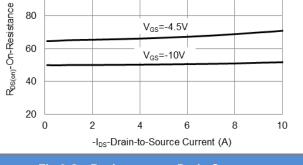
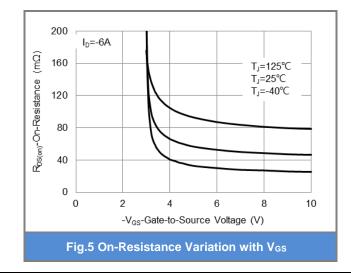
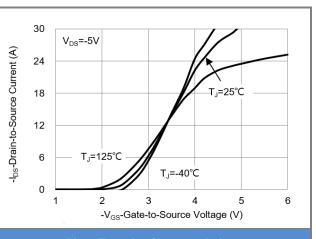


Fig.3 On-Resistance vs. Drain Current





**Fig.2 Transfer Characteristics** 

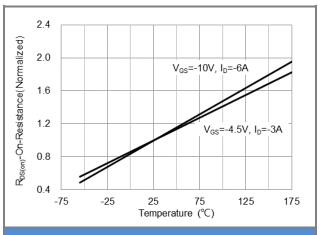
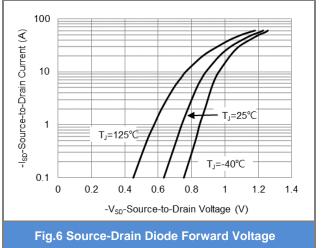


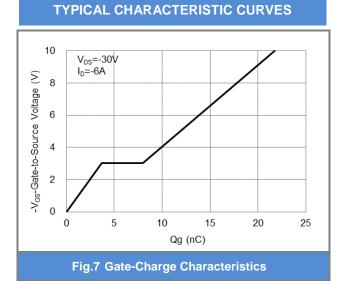
Fig.4 On-Resistance vs. Junction temperature

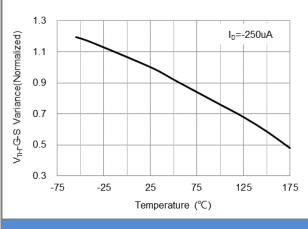


SEMI CONDUCTOR

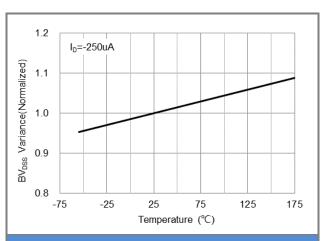
PΛN

### PJQ44609AP-AU





#### Fig.9 Threshold Voltage Variation with Temperature





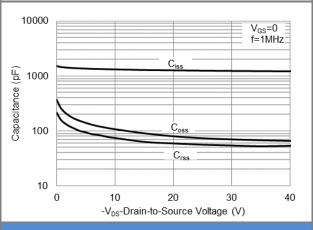
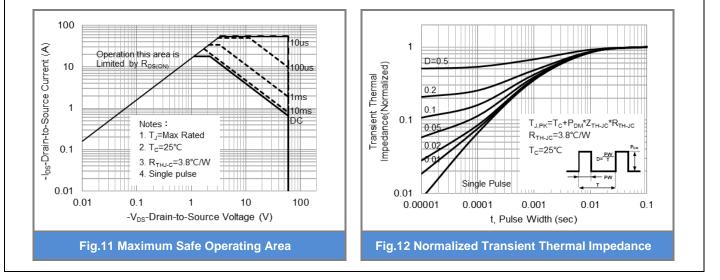


Fig.10 Capacitance vs. Drain-Source Voltage



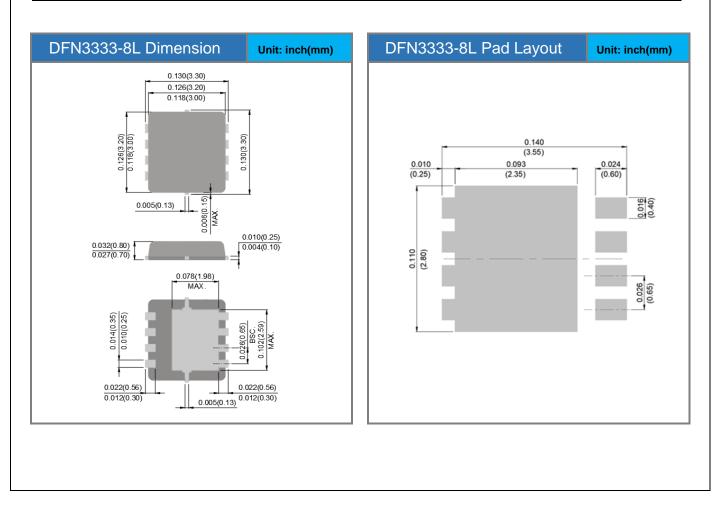


## PJQ44609AP-AU

#### **Product and Packing Information**

Part No.	Package Type	Packing Type	Marking	
PJQ44609AP-AU	DFN3333-8L	5K pcs / 13" reel	44609A	

#### Packaging Information & Mounting Pad Layout





### PJQ44609AP-AU

### Disclaimer

- Reproducing and modifying information of the document is prohibited without permission from Panjit International Inc..
- Panjit International Inc. reserves the rights to make changes of the content herein the document anytime without notification. Please refer to our website for the latest document.
- Panjit International Inc. disclaims any and all liability arising out of the application or use of any product including damages incidentally and consequentially occurred.
- Panjit International Inc. does not assume any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.
- Applications shown on the herein document are examples of standard use and operation. Customers are responsible in comprehending the suitable use in particular applications. Panjit International Inc. makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.
- The products shown herein are not designed and authorized for equipments relating to human life and for any applications concerning life-saving or life-sustaining, such as medical instruments, aerospace machinery et cetera. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Panjit International Inc. for any damages resulting from such improper use or sale.
- Since Panjit uses lot number as the tracking base, please provide the lot number for tracking when complaining.